Abstract

Wire Guide Roll for Wire Saw

The invention relates to a wire guide roll for use in wire saws for simultaneously slicing a multiplicity of wafers from a cylindrical workpiece, which is provided with a coating having a thickness of at least 2 mm and at most 7.5 mm and consisting of a material which has a Shore A hardness of at least 60 and at most 99, and which furthermore contains a multiplicity of grooves through which the sawing wire is guided, wherein the grooves each have a curved groove base with a radius of curvature R which is given by 0.25-1.6 times a sawing wire diameter D, and an aperture angle a of 60-130°. The invention furthermore relates to a method for simultaneously slicing a multiplicity of wafers from a cylindrical workpiece by means of a wire saw, with the use of such wire guide rolls.